PMEG3010AESB

30 V, 1 A low VF MEGA Schottky barrier rectifier

18 June 2015 — Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection in a leadless ultra small DSN1006-2 (SOD993) Surface-Mounted Device (SMD) package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1$ A
- Reverse voltage: $V_R \leq 30$ V
- Low forward voltage, typical: $V_F = 415$ mV
- Low reverse current, typical: $I_R = 300$ µA
- Package height typ. 270 µm

3. Applications

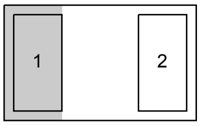
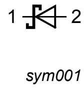
- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	δ = 0.5 ; f = 20 kHz; $T_{sp} \leq 145$ °C; square wave		-	-	1	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	30	V
V_F	forward voltage	$I_F = 1$ A; $t_p \leq 300$ µs; δ ≤ 0.02 ; $T_j = 25$ °C		-	415	480	mV
I_R	reverse current	$V_R = 20$ V; $t_p \leq 3$ ms; δ ≤ 0.3 ; $T_j = 25$ °C		-	60	255	µA
		$V_R = 30$ V; $t_p \leq 3$ ms; δ ≤ 0.3 ; $T_j = 25$ °C		-	300	1250	µA

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 Transparent top view **DSN1006-2 (SOD993)**	
2	A	anode		

[1] The marking bar indicates the cathode.

5. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3010AESB	DSN1006-2	DSN1006-2, leadless ultra small package; 2 terminals; body 1.0 x 0.6 x 0.27 mm	SOD993

6. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3010AESB	3A

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	T_j = 25 °C		-	30	V
I_F	forward current	T_{sp} ≤ 140 °C; δ = 1		-	1.4	A
$I_{F(AV)}$	average forward current	δ = 0.5 ; f = 20 kHz; T_{amb} ≤ 115 °C; square wave	[1]	-	1	A
		δ = 0.5 ; f = 20 kHz; T_{sp} ≤ 145 °C; square wave		-	1	A
I_{FRM}	repetitive peak forward current	t_p ≤ 1 ms; δ ≤ 0.25		-	4	A
I_{FSM}	non-repetitive peak forward current	t_p = 8 ms; $T_{j(init)}$ = 25 °C; square wave		-	10	A
P_{tot}	total power dissipation	T_{amb} ≤ 25 °C	[2]	-	0.525	W
			[3]	-	1	W
			[1]	-	1.78	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

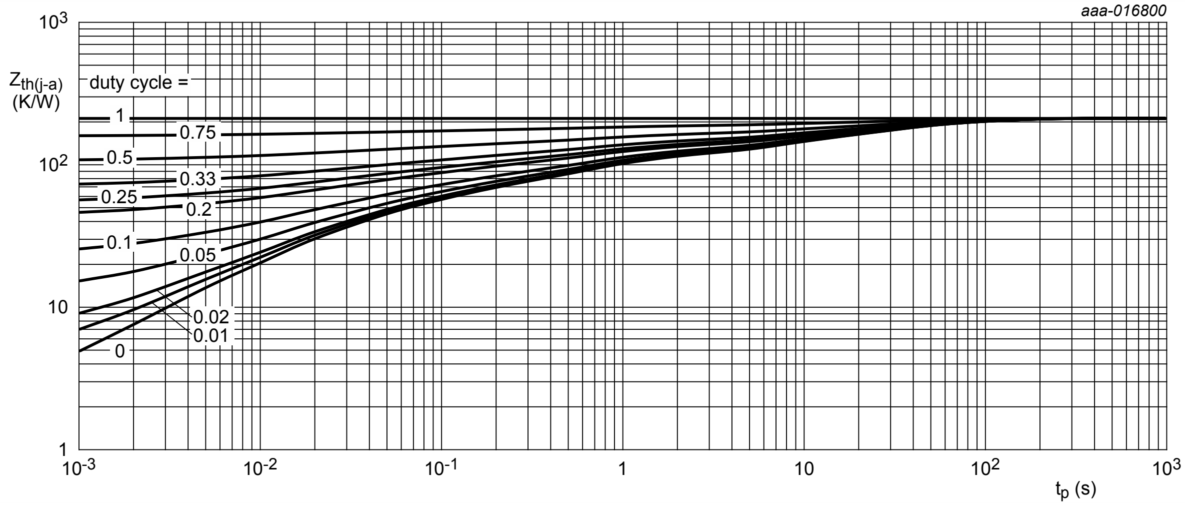
[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm^2 each.

8. Thermal characteristics

Table 6. Thermal characteristics

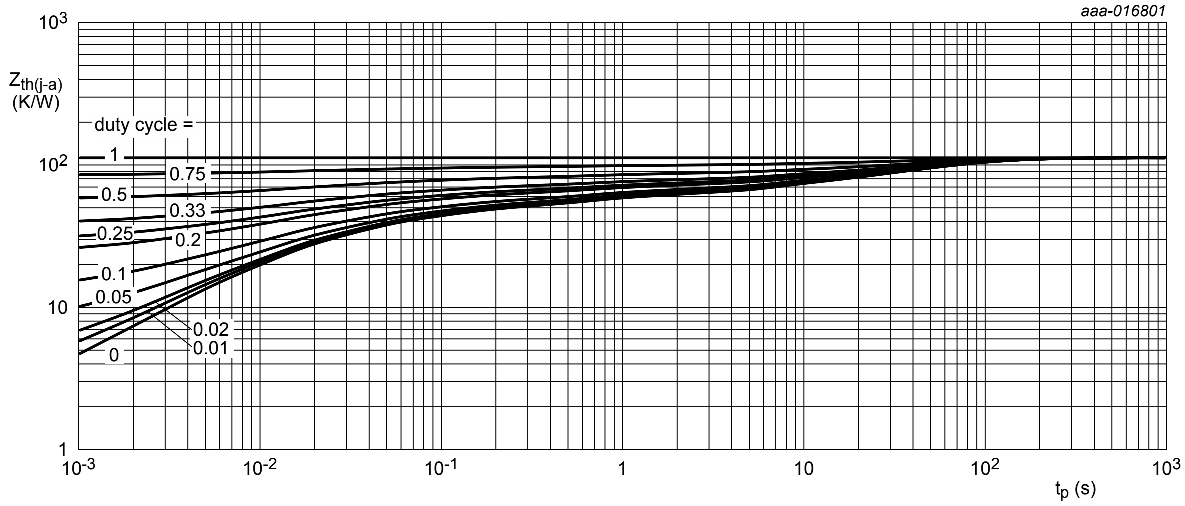
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	240	K/W
			[1][3]	-	-	125	K/W
			[1][4]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	15	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for anode and cathode 1 cm^2 each.
[4] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[5] Soldering point of anode tab.



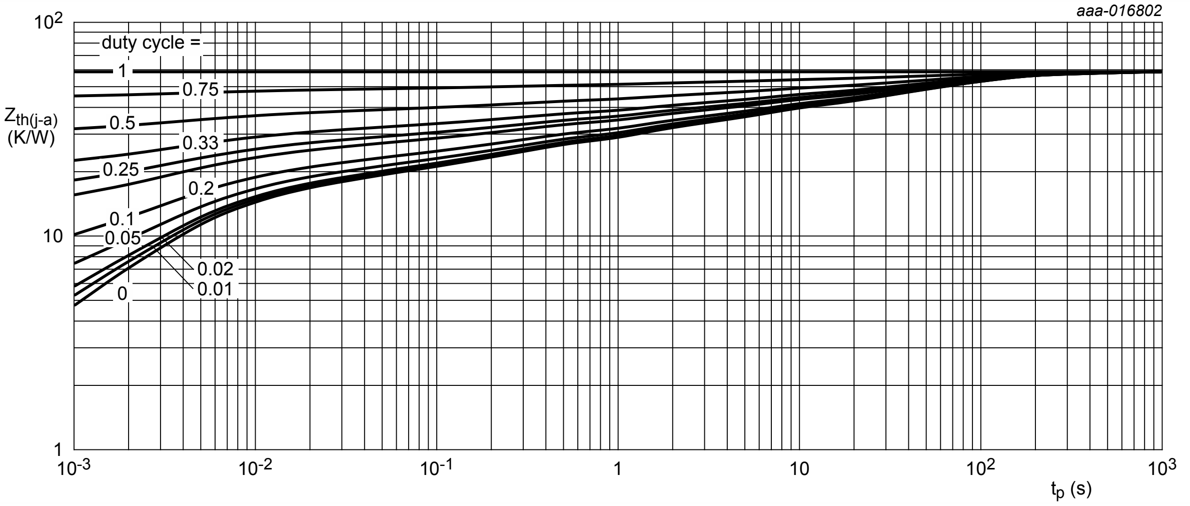
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for anode and cathode 1 cm^2 each

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al_2O_3, standard footprint

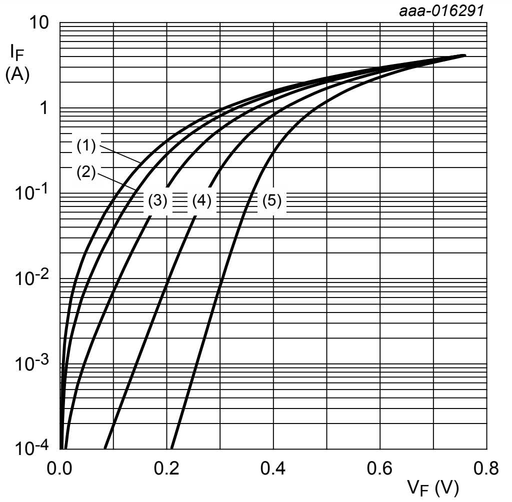
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

9. Characteristics

Table 7. Characteristics

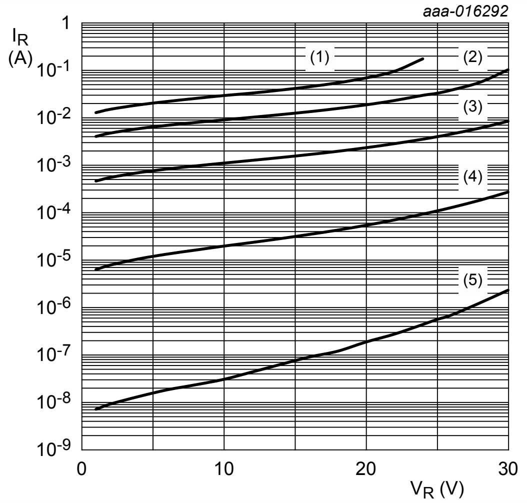
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	I_R = 10 mA; t_p = 300 µs; δ = 0.02 ; T_j = 25 °C		30	-	-	V
V_F	forward voltage	I_F = 1 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	140	-	mV
		I_F = 10 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	200	-	mV
		I_F = 100 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	270	325	mV
		I_F = 200 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	300	-	mV
		I_F = 500 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	355	405	mV
		I_F = 700 mA; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	380	-	mV
		I_F = 1 A; t_p ≤ 300 µs; δ ≤ 0.02 ; T_j = 25 °C		-	415	480	mV
I_R	reverse current	V_R = 5 V; t_p ≤ 3 ms; δ ≤ 0.3 ; T_j = 25 °C		-	13	-	µA
		V_R = 10 V; t_p ≤ 3 ms; δ ≤ 0.3 ; T_j = 25 °C		-	22	90	µA
		V_R = 20 V; t_p ≤ 3 ms; δ ≤ 0.3 ; T_j = 25 °C		-	60	255	µA

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		V_R = 30 V; t_p ≤ 3 ms; δ ≤ 0.3 ; T_j = 25 °C		-	300	1250	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C		-	86	-	pF
		V_R = 10 V; f = 1 MHz; T_j = 25 °C		-	32	-	pF
t_{rr}	reverse recovery time	I_F = 0.5 A; I_R = 0.5 A; $I_{R(meas)}$ = 0.1 A; T_j = 25 °C		-	3.5	-	ns



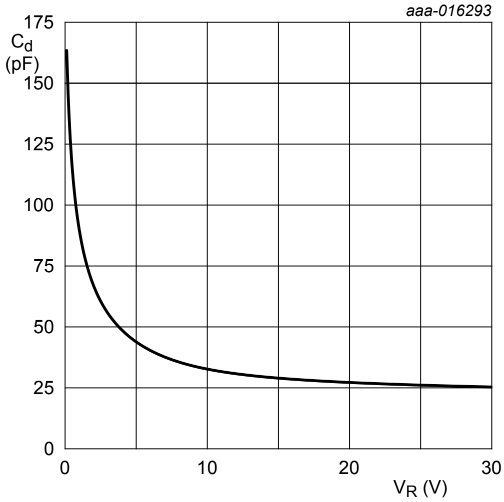
pulsed condition
(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = −40 °C

Fig. 4. Forward current as a function of forward voltage; typical values



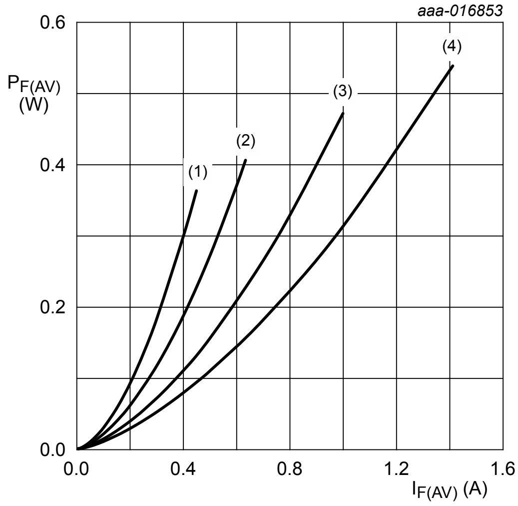
pulsed condition
(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = −40 °C

Fig. 5. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



T_j = 150 °C

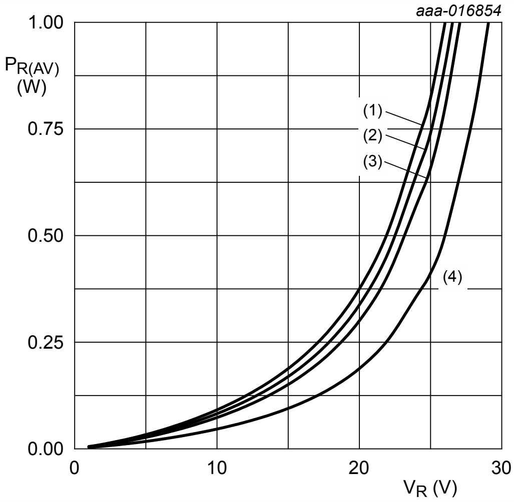
(1) δ = 0.1

(2) δ = 0.2

(3) δ = 0.5

(4) δ = 1

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



T_j = 125 °C

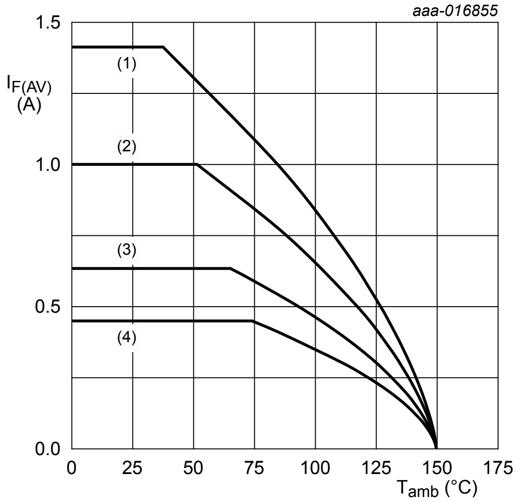
(1) δ = 1

(2) δ = 0.9

(3) δ = 0.8

(4) δ = 0.5

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_j = 150 °C

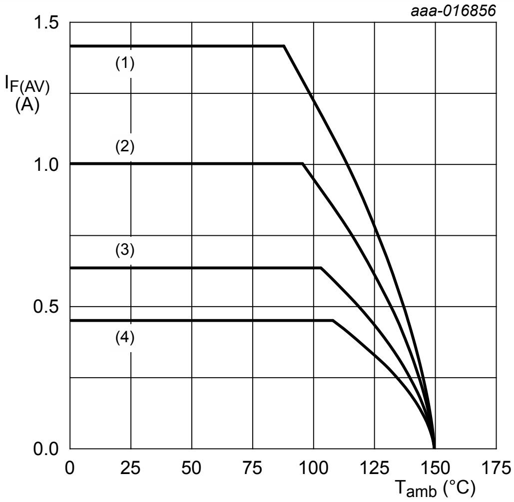
(1) δ = 1; DC

(2) δ = 0.5; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for anode and cathode 1 cm^2 each

T_j = 150 °C

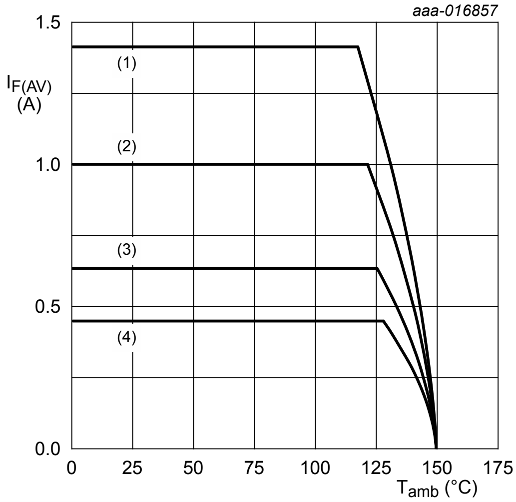
(1) δ = 1; DC

(2) δ = 0.5; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3, standard footprint

T_j = 150 °C

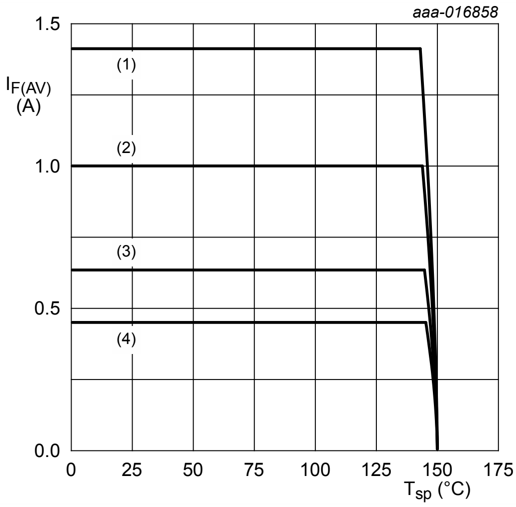
(1) δ = 1 (DC)

(2) δ = 0.5; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



T_j = 150 °C

(1) δ = 1 (DC)

(2) δ = 0.5; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

(4) δ = 0.1; f = 20 kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

10. Test information

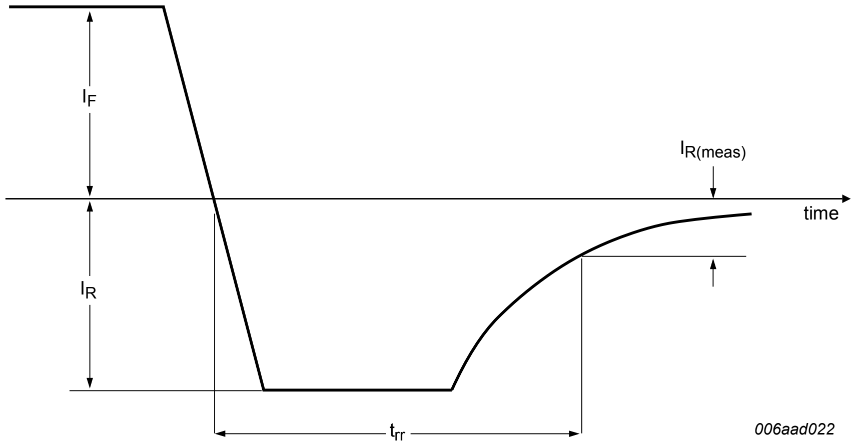


Fig. 13. Reverse recovery definition; step recovery

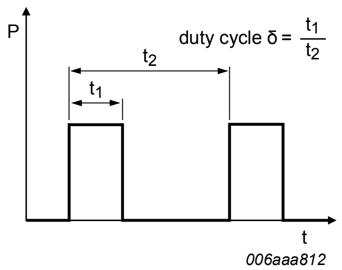


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

11. Package outline

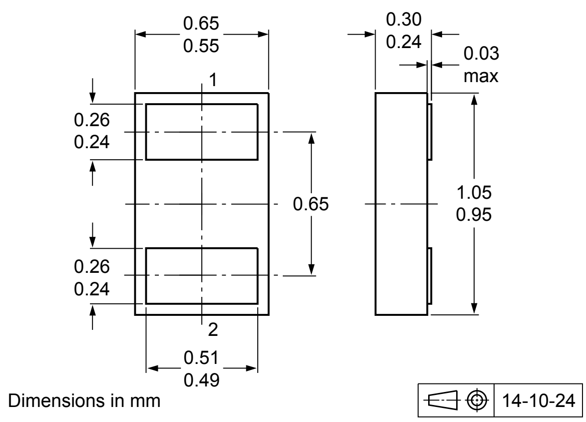


Fig. 15. Package outline DSN1006-2 (SOD993)

12. Soldering

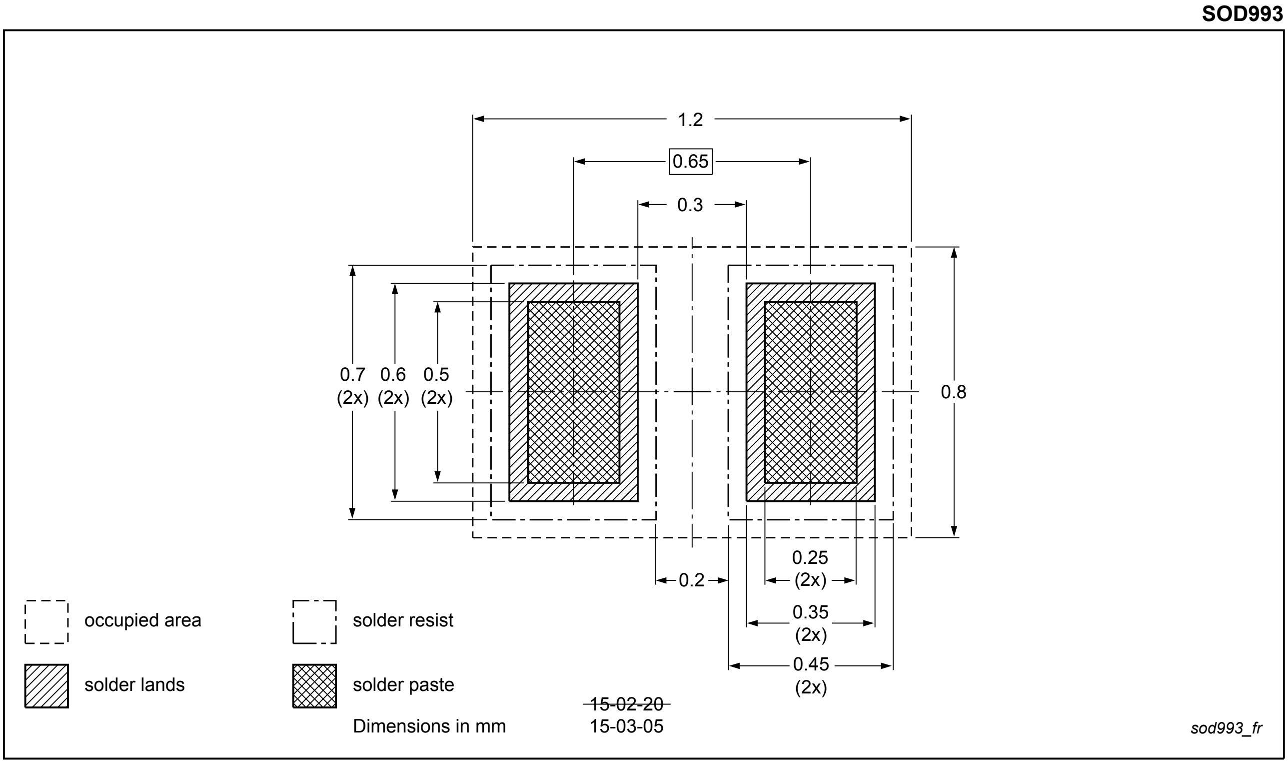


Fig. 16. Reflow soldering footprint for DSN1006-2 (SOD993)

13. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3010AESB v.2	20150618	Product data sheet	-	PMEG3010AESB v.1
Modifications:	• Changed product status to "Product data sheet"			
PMEG3010AESB v.1	20150506	Preliminary data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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